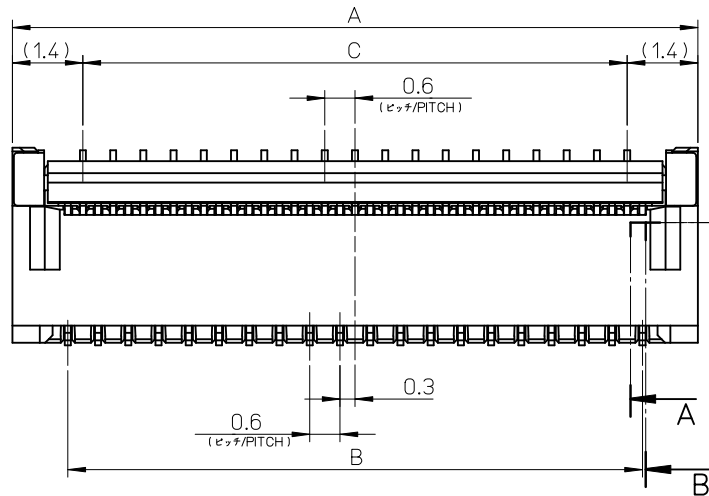
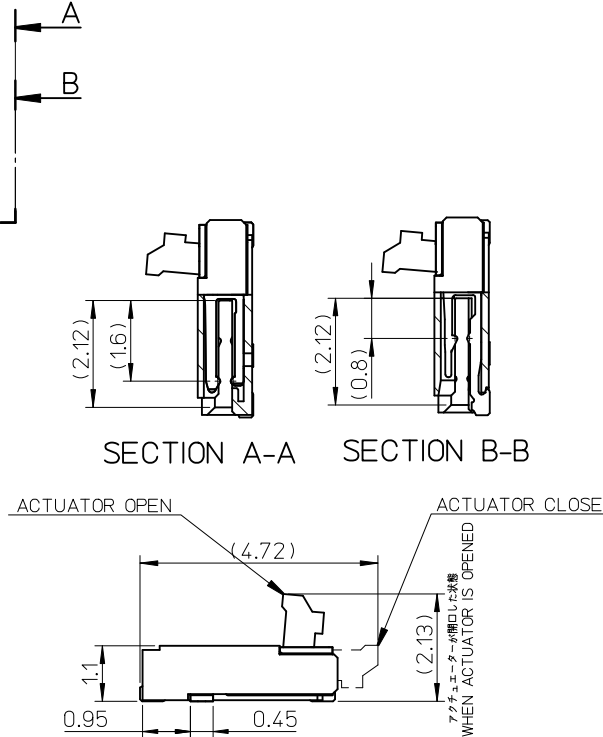


斜視図
SCALE 5:1



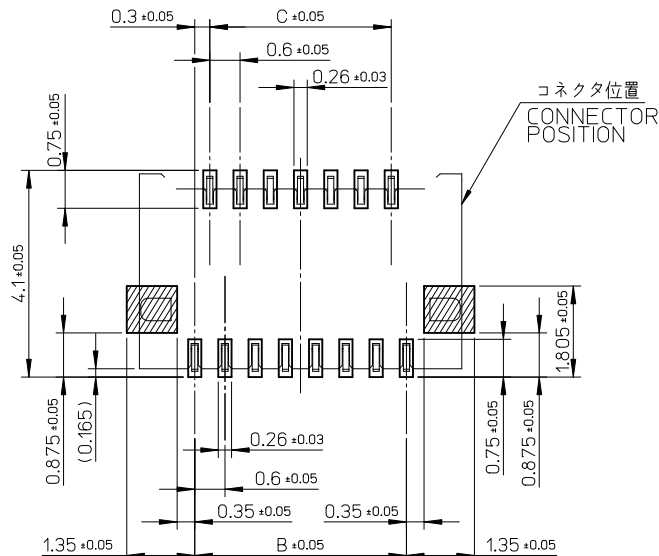
部品構成
PART COMPOSITION

- ハウジング: 液晶ポリマー (LCP), ガラス充填, UL94 V-0, ナチュラル (白)
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金
ODD TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD OVER NICKEL PLATING NI STRIPE (BARRIER)
- 偶数ターミナル: 銅合金
EVEN TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD OVER NICKEL PLATING NI STRIPE (BARRIER)
- アクチュエータ...材質: ポリアミド(PA) 黒色 UL94V-0
ACTUATOR MATERIAL: POLYAMIDE(PA) BLACK UL94-V0
- ネイル...材質: 燐青銅
NAIL MATERIAL: PHOSPHOR BRONZE
処理: ニッケル下地すずめっき
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品
ELV & RoHS COMPLIANT

15.6	14.4	15	17.2	502350-5100	51
14.4	13.2	13.8	16.0	502350-4700	47
13.8	12.6	13.2	15.4	502350-4500	45
12.6	11.4	12	14.2	502350-4100	41
12	10.8	11.4	13.6	502350-3900	39
11.4	10.2	10.8	13	502350-3700	37
10.2	9	9.6	11.8	502350-3300	33
9.6	8.4	9	11.2	502350-3100	31
7.2	6	6.6	8.8	502350-2300	23
6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 502350-**09

REVISED EC NO: J2011-0598 DRW:N.SHIRATA 2010/10/19 CHKD:K.TAKAHASHI 2010/10/19 APPR:KMORI KAWA 2010/10/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE				
		10 OVER 30 UNDER	± 0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502350-001		1 OF 2			
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN
DIM.(REF.)

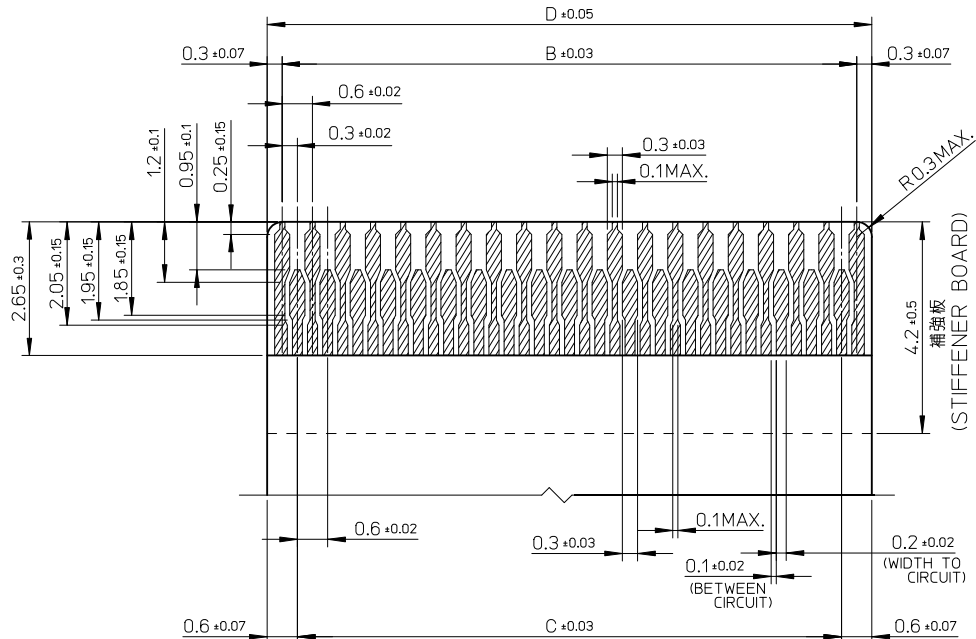
推奨メタルマスク厚さ : 0.1mm
RECOMMENDED METAL MASK THICKNESS : 0.1mm
推奨開口率 : 100%
APERTURE RATE : 100%

注記
NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて
ABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
導体部については軟銅箔35μmまたは50μmを推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

- 平坦度は0.1以下
COPLANARITY TO BE 0.1 MAXIMUM



適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03
APPLY FPC
RECOMMENDED DIM.
THICKNESS : 0.2±0.03

補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

めっき: 金めっき (0.1μm以上)
下地: ニッケル (1-5μm)
PLATING: GOLD (0.1μm MIN.)
NICKEL UNDER (1-5μm)

FPC構成推奨仕様
STRUCTURE OF FPC

REVISED EC NO.: J2011-0598 DWG:SHIRATA CHK:KAKAHASHI APP:KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
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		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25					
		ANGULAR ±3 °		MATERIAL NO.		MOLEX INCORPORATED				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART1		DOCUMENT NO. SD-502350-001					
	REV			SIZE A3		SHEET NO. 2 OF 2				

